

# Isolated Feedback Generator

## FEATURES

- An Amplitude-Modulation System for Transformer Coupling an Isolated Feedback Error Signal
- Low-Cost Alternative to Optical Couplers
- Internal 1% Reference and Error Amplifier
- Internal Carrier Oscillator Usable to 5MHz
- Modulator Synchronizable to an External Clock
- Loop Status Monitor

## DESCRIPTION

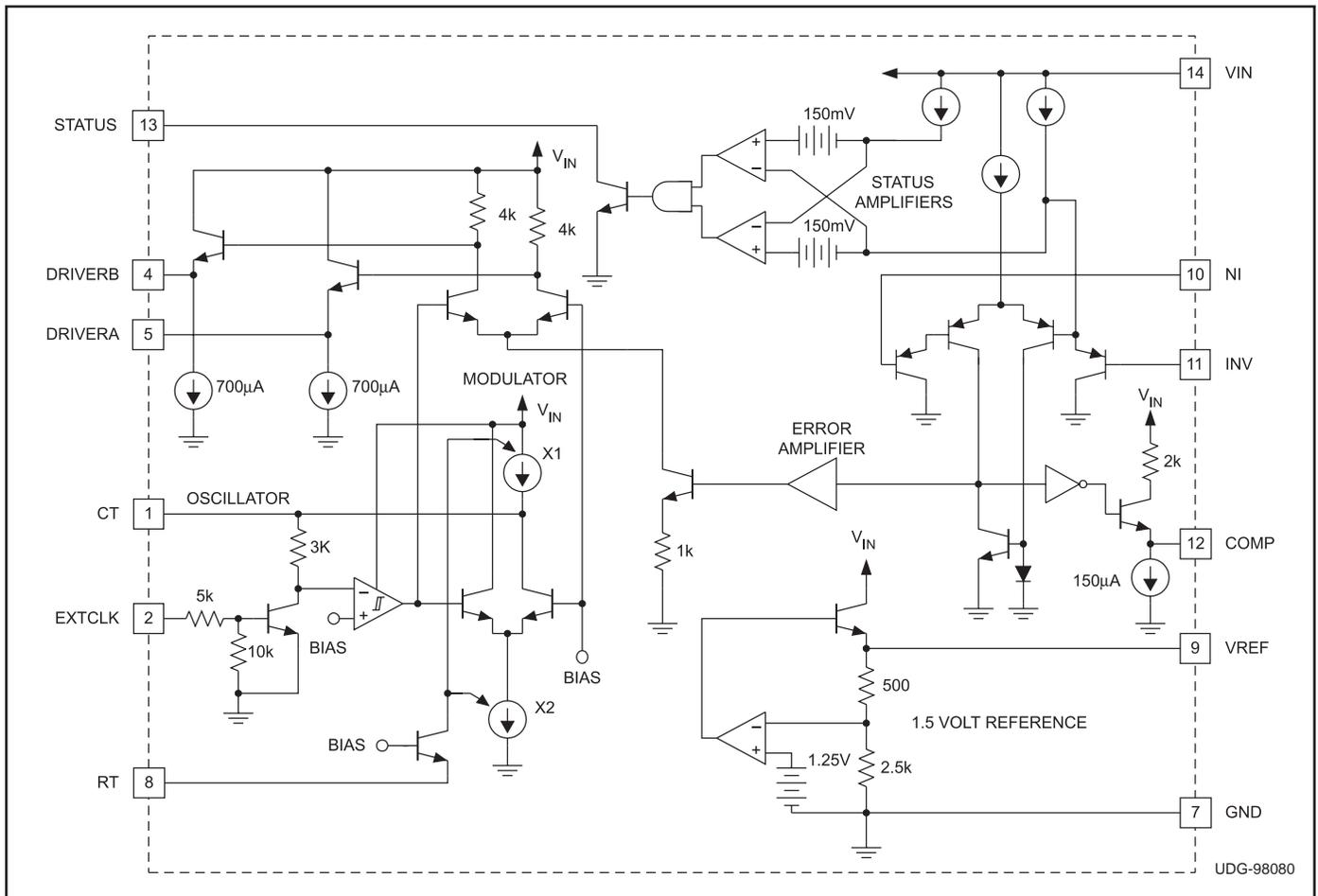
The UC1901 family is designed to solve many of the problems associated with closing a feedback control loop across a voltage isolation boundary. As a stable and reliable alternative to an optical coupler, these devices feature an amplitude modulation system which allows a loop error signal to be coupled with a small RF transformer or capacitor.

The programmable, high-frequency oscillator within the UC1901 series permits the use of smaller, less expensive transformers which can readily be built to meet the isolation requirements of today's line-operated power systems. As an alternative to RF operation, the external clock input to these devices allows synchronization to a system clock or to the switching frequency of a SMPS.

An additional feature is a status monitoring circuit which provides an active-low output when the sensed error voltage is within  $\pm 10\%$  of the reference. The DRIVERB output, DRIVERA output, and STATUS output are disabled until the input supply has reached a sufficient level to allow proper operation of the device.

Since these devices can also be used as a DC driver for optical couplers, the benefits of 4.5 to 40V supply operation, a 1% accurate reference, and a high gain general purpose amplifier offer advantages even though an AC system may not be desired.

## UC1901 SIMPLIFIED SCHEMATIC



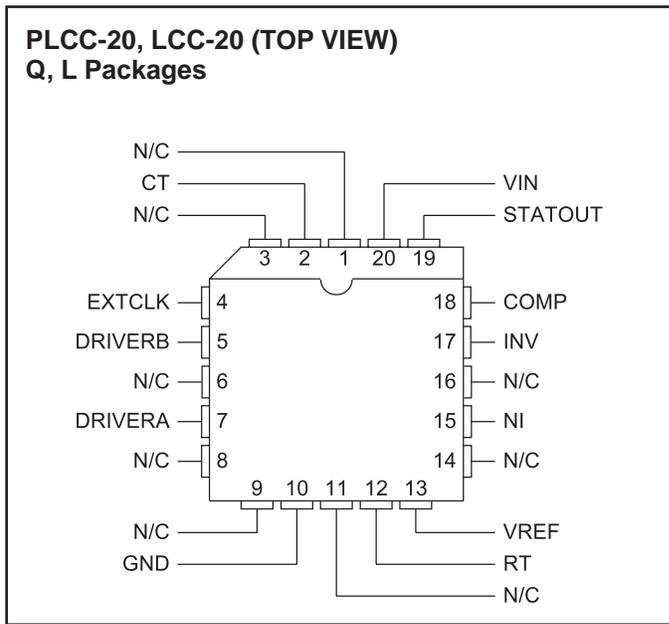
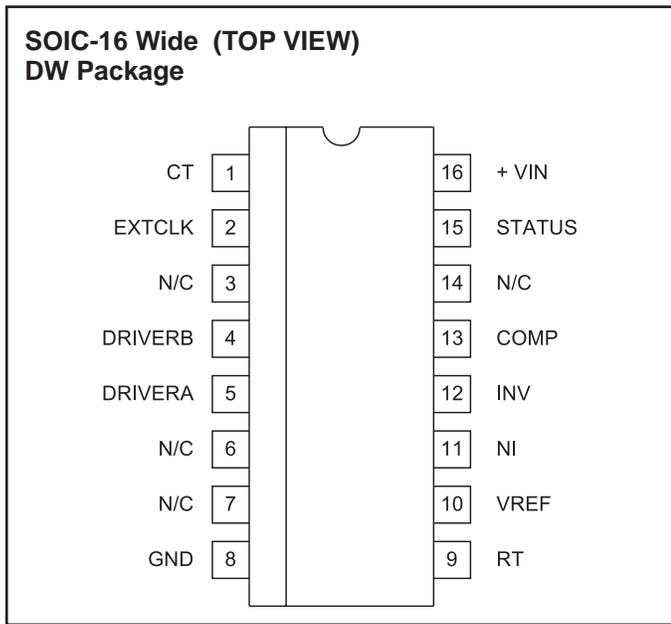
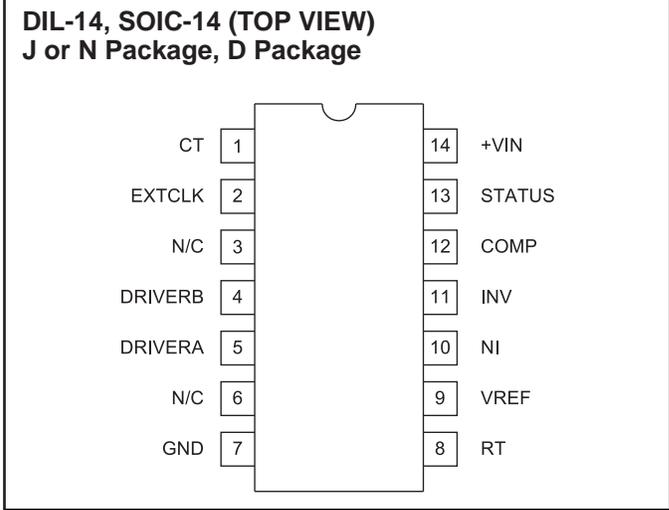
### ABSOLUTE MAXIMUM RATINGS (Note 1)

Input Supply Voltage, $V_{IN}$ .....	40V
Reference Output Current .....	-10mA
Driver Output Currents .....	-35mA
Status Indicator Voltage .....	40V
Status Indicator Current .....	20mA
Ext. Clock Input .....	40V
Error Amplifier Inputs .....	-0.5V to +35V
Power Dissipation at $T_A = 25^\circ\text{C}$ .....	1000mW
Power Dissipation at $T_c = 25^\circ\text{C}$ .....	2000mW
Operating Junction Temperature .....	-55°C to +150°C
Storage Temperature .....	-65°C to +150°C
Lead Temperature (Soldering, 10 seconds) .....	300°C

**Note 1:** Voltages are referenced to ground, Pin 7. Currents are positive into, negative out of the specified terminal.

**Note 2:** Consult Packaging section of Databook for thermal limitations and considerations of package.

### CONNECTION DIAGRAMS



### TEMPERATURE AND PACKAGE SELECTION GUIDE

	TEMPERATURE RANGE	AVAILABLE PACKAGES
UC1901	-55°C to +125°C	J, L
UC2901	-40°C to +85°C	D, DW, J, N, Q
UC3901	0°C to +70°C	D, DW, J, N, Q

**ELECTRICAL CHARACTERISTICS** Unless otherwise stated, these specifications apply for  $V_{IN} = 10V$ ,  $R_T = 10k\Omega$ ,  $C_T = 820pF$ ,  $T_A = T_J$ .

PARAMETER	TEST CONDITIONS	UC1901/UC2901			UC3901			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>Reference Section</b>								
Output Voltage	$T_J = 25^\circ C$	1.485	1.5	1.515	1.47	1.5	1.53	V
	$T_{MIN} \leq T_J \leq T_{MAX}$	1.470	1.5	1.530	1.455	1.5	1.545	
Line Regulation	$V_{IN} = 4.5$ to $35V$		2	10		2	15	mV
Load Regulation	$I_{OUT} = 0$ to $5mA$		4	10		4	15	mV
Short Circuit Current	$T_J = 25^\circ C$		-35	-55		-35	-55	mV
<b>Error Amplifier Section (To Compensation Terminal)</b>								
Input Offset Voltage	$V_{CM} = 1.5V$		1	4		1	8	mV
Input Bias Current	$V_{CM} = 1.5V$		-1	-3		-1	-6	$\mu A$
Input Offset Current	$V_{CM} = 1.5V$		0.1	1		0.1	2	$\mu A$
Small Signal Open Loop Gain		40	60		40	60		dB
CMRR	$V_{CM} = 0.5$ to $7.5V$	60	80		60	80		dB
PSRR	$V_{IN} = 2$ to $25V$	80	100		80	100		dB
Output Swing, $\Delta V_o$		0.4	0.7		0.4	0.7		V
Maximum Sink Current		90	150		90	150		$\mu A$
Maximum Source Current		-2	-3		-2	-3		mA
Gain Band Width Product			1			1		MHz
Slew Rate			0.3			0.3		V/ $\mu S$
<b>Modulators/Drivers Section (From Compensation Terminal)</b>								
Voltage Gain		11	12	13	10	12	14	dB
Output Swing		$\pm 1.6$	$\pm 2.8$		$\pm 1.6$	$\pm 2.8$		V
Driver Sink Current		500	700		500	700		$\mu A$
Driver Source Current		-15	-35		-15	-35		mA
Gain Band Width Product			25			25		MHz
<b>Oscillator Section</b>								
Initial Accuracy	$T_J = 25^\circ C$	140	150	160	130	150	170	kHz
	$T_{MIN} \leq T_J \leq T_{MAX}$	130		170	120		180	kHz
Line Sensitivity	$V_{IN} = 5$ to $35V$		.15	.35		.15	.60	%/V
Maximum Frequency	$R_T = 10k$ , $C_T = 10pF$		5			5		MHz
Ext. Clock Low Threshold	Pin 1 ( $C_T$ ) = $V_{IN}$	0.5			0.5			V
Ext. Clock High Threshold	Pin 1 ( $C_T$ ) = $V_{IN}$			1.6			1.6	V
<b>Status Indicator Section</b>								
Input Voltage Window	@ E/A Inputs, $V_{CM} = 1.5V$	$\pm 135$	$\pm 150$	$\pm 165$	$\pm 130$	$\pm 150$	$\pm 170$	mV
Saturation Voltage	E/A $\Delta$ Input = $0V$ , $I_{SINK} = 1.6mA$			0.45			0.45	V
Max. Output Current	Pin 13 = $3V$ , E/A $\Delta$ Input = $0.0V$	8	15		8	15		mA
Leakage Current	Pin 13 = $40V$ , E/A $\Delta$ Input = $0.2V$		.05	1		.05	5	$\mu A$
Supply Current	$V_{IN} = 35V$		5	8		5	10	mA
<b>UVLO Section</b>								
Drivers Enabled Threshold	At Input Supply $V_{IN}$		3.9	4.5		3.9	4.5	V
Status Output Enabled Threshold	At Input Supply $V_{IN}$		3.9	4.5		3.9	4.5	V
Change in Reference Output	When $V_{IN}$ Reaches UVLO Threshold		-2	-30		-2	-30	mV

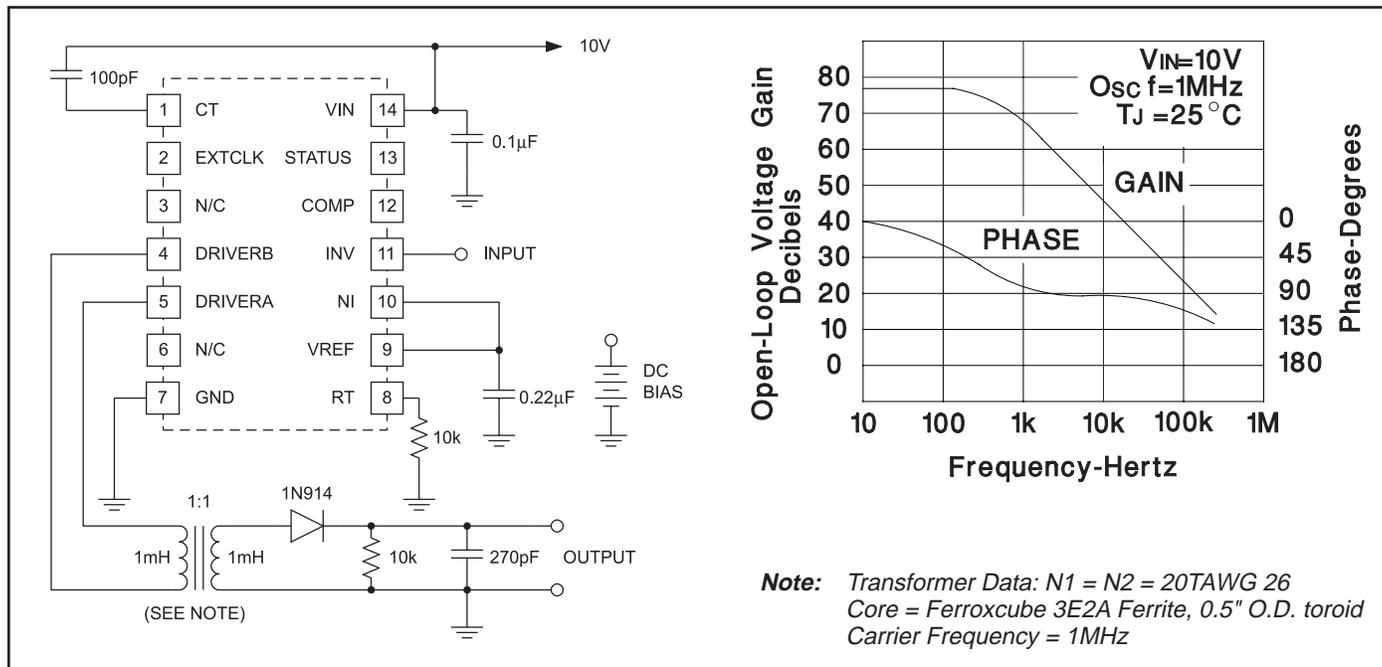


Figure 1. Transformer Coupled Open Loop Transfer Function

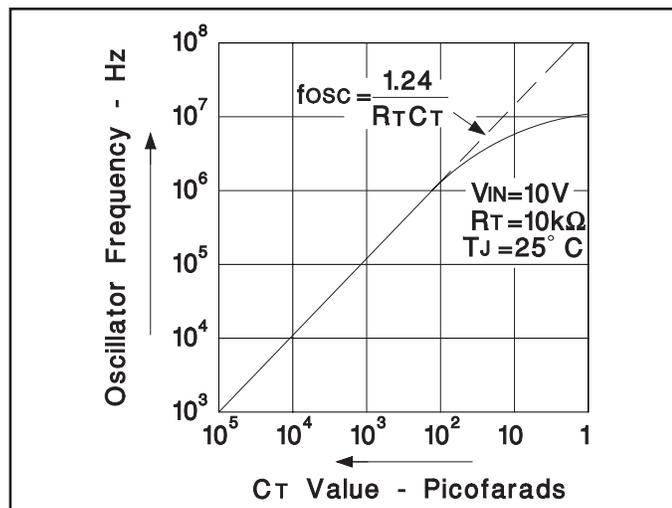


Figure 2. Oscillator Frequency

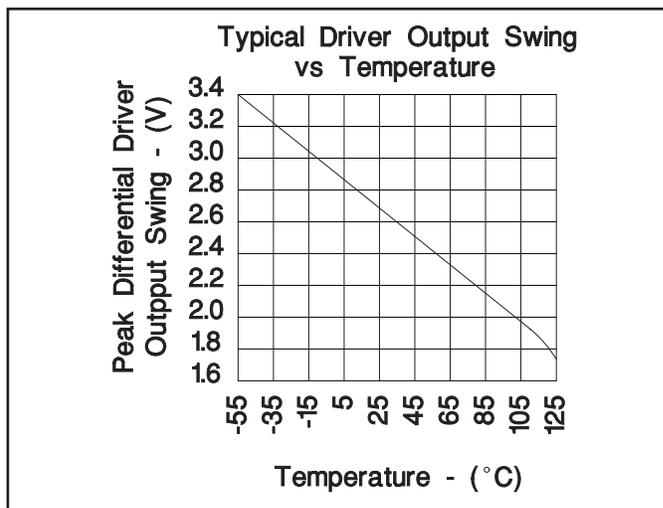


Figure 3. Typical Driver Output Swing vs Temperature

## APPLICATION INFORMATION

The error amplifier compensation terminal, Pin 12, is intended as a source of feedback to the amplifier's inverting input at Pin 11. For most applications, a series DC blocking capacitor should be part of the feedback network. The amplifier is internally compensated for unity feedback.

The waveform at the driver outputs is a squarewave with an amplitude that is proportional to the error amplifier input signal. There is a fixed 12dB of gain from the error amplifier compensation pin to the modulator driver outputs. The frequency of the output waveform is controlled by either the internal oscillator or an external clock signal.

With the internal oscillator the squarewave will have a fixed 50% duty cycle. If the internal oscillator is disabled by connecting Pin 1,  $C_R$ , to  $V_{IN}$  then the frequency and duty cycle of the output will be determined by the input clock waveform at Pin 2. If the oscillator remains disabled and there is not clock input at Pin 2, there will be a linear 12dB of signal gain to one or the other of the driver outputs depending on the DC state of Pin 2.

The driver outputs are emitter followers which will source a minimum of 15mA of current. The sink current, internally limited at 700 $\mu$ A, can be increased by adding resistors to ground at the driver outputs.

APPLICATION INFORMATION (continued)

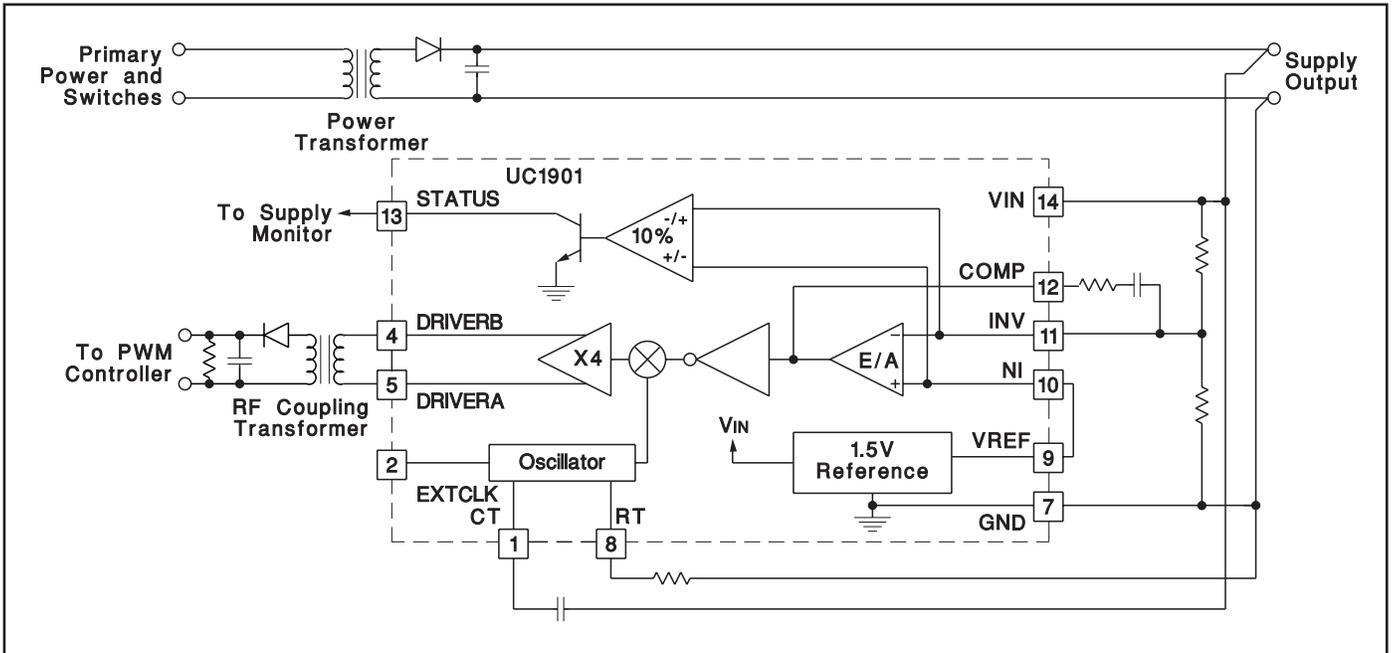


Figure 4. R.F. Transformer Coupled Feedback

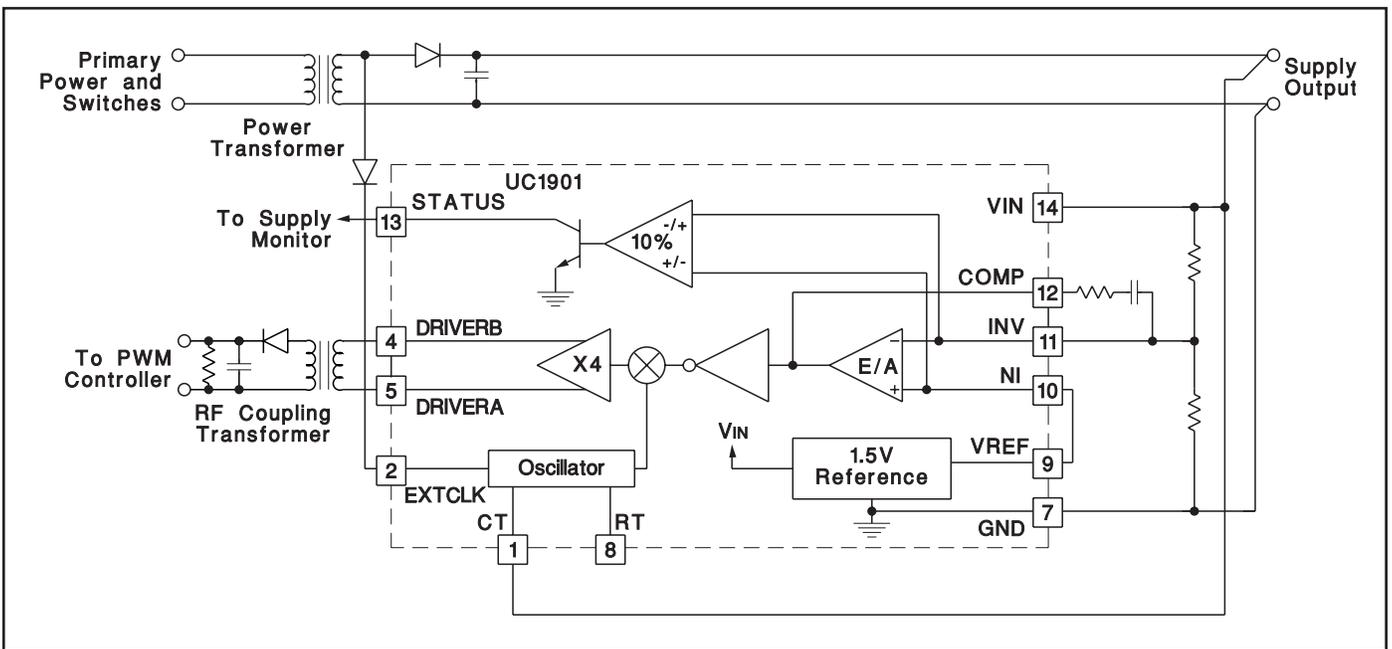


Figure 5. Feedback Coupled at Switching Frequency

TYPICAL APPLICATION

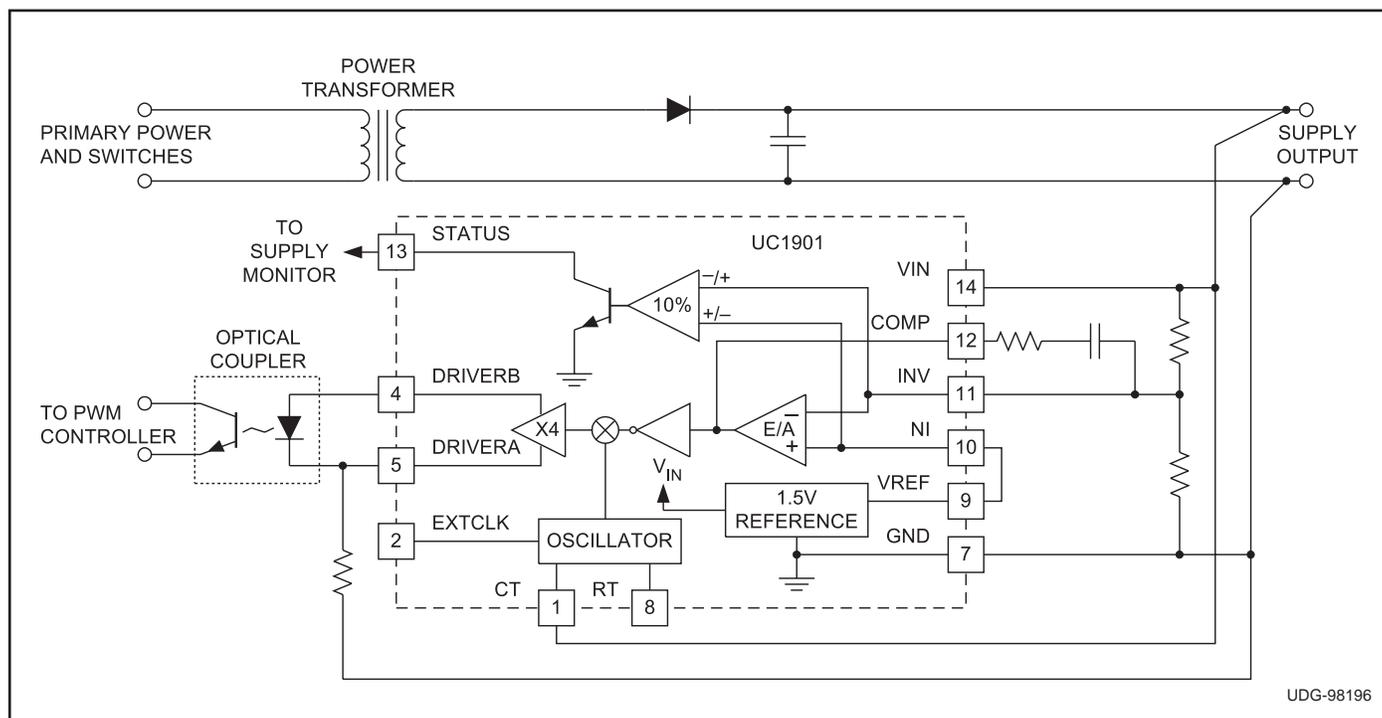


Figure 6. Optically Coupled DC Feedback

PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-89441012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	Level-NC-NC-NC
5962-8944101CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	Level-NC-NC-NC
5962-8944101VCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
UC1901J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	Level-NC-NC-NC
UC1901J883B	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	Level-NC-NC-NC
UC1901L	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	Level-NC-NC-NC
UC1901L883B	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	Level-NC-NC-NC
UC2901D	ACTIVE	SOIC	D	14	50	TBD	CU NIPDAU	Level-1-220C-UNLIM
UC2901DTR	ACTIVE	SOIC	D	14	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
UC2901DW	ACTIVE	SOIC	DW	16	40	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UC2901DWTR	ACTIVE	SOIC	DW	16	2000	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UC2901J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	Level-NC-NC-NC
UC2901N	ACTIVE	PDIP	N	14	25	TBD	CU NIPDAU	Level-NA-NA-NA
UC2901Q	ACTIVE	PLCC	FN	20	46	TBD	CU SNPB	Level-2-220C-1 YEAR
UC2901QTR	ACTIVE	PLCC	FN	20	1000	TBD	CU SNPB	Level-2-220C-1 YEAR
UC3901D	ACTIVE	SOIC	D	14	50	TBD	CU NIPDAU	Level-1-220C-UNLIM
UC3901DTR	ACTIVE	SOIC	D	14	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
UC3901DW	ACTIVE	SOIC	DW	16	40	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UC3901DWTR	ACTIVE	SOIC	DW	16	2000	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UC3901DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	Level-NC-NC-NC
UC3901N	ACTIVE	PDIP	N	14	25	TBD	CU NIPDAU	Level-NA-NA-NA
UC3901Q	ACTIVE	PLCC	FN	20	46	TBD	CU SNPB	Level-2-220C-1 YEAR
UC3901QTR	ACTIVE	PLCC	FN	20	1000	TBD	CU SNPB	Level-2-220C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

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**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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5962-89441012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8944101CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8944101VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
UC1901J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
UC1901J883B	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
UC1901L	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
UC1901L883B	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
UC2901D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2901DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2901DTR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2901DTRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2901DWG4	ACTIVE	SOIC	DW	16		TBD	Call TI	Call TI
UC2901DWTRG4	ACTIVE	SOIC	DW	16		TBD	Call TI	Call TI
UC2901J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
UC2901N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2901NG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2901Q	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC2901QG3	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC3901D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901DTR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901DTRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3901N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3901NG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3901Q	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR

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UC3901QG3	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC3901QTR	ACTIVE	PLCC	FN	20	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC3901QTRG3	ACTIVE	PLCC	FN	20	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

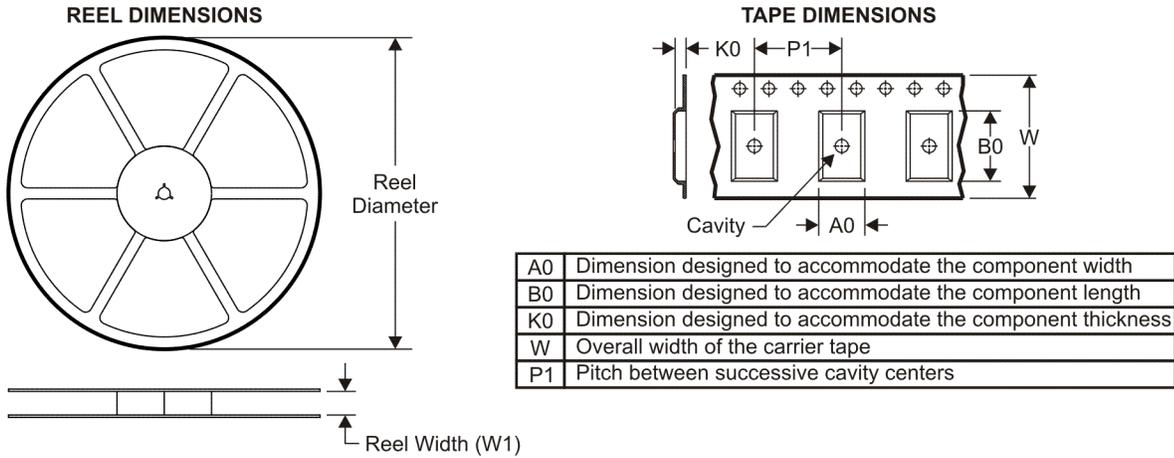
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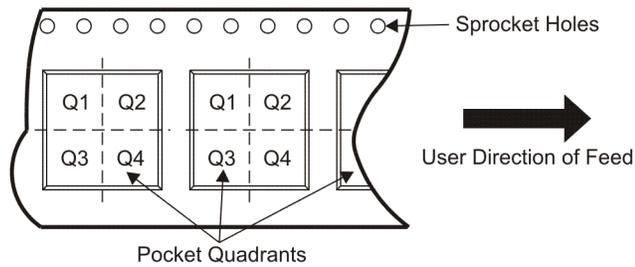
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**TAPE AND REEL INFORMATION**



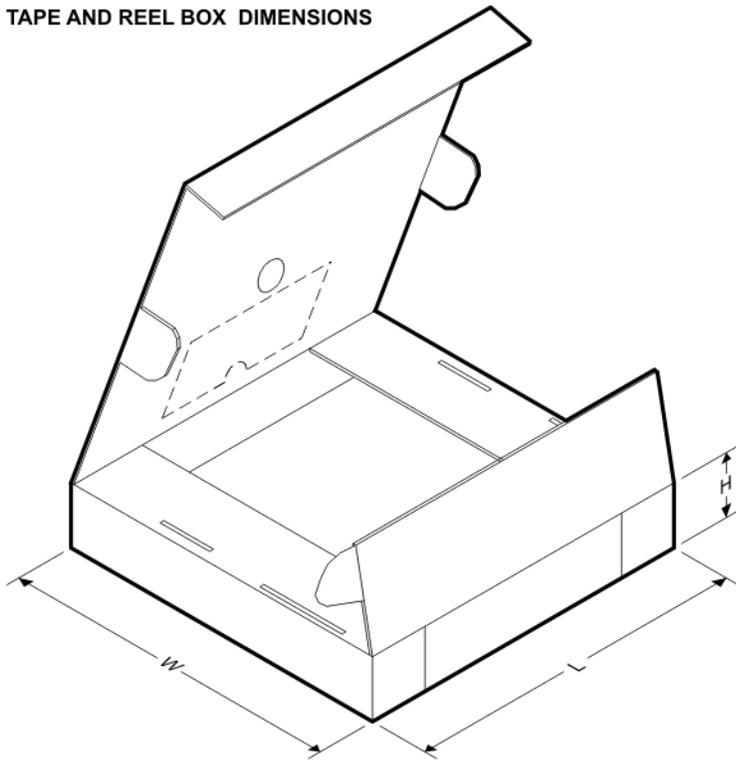
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2901DTR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
UC3901DTR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
UC3901DWTR	SOIC	DW	16	2000	330.0	16.4	10.85	10.8	2.7	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2901DTR	SOIC	D	14	2500	346.0	346.0	33.0
UC3901DTR	SOIC	D	14	2500	346.0	346.0	33.0
UC3901DWTR	SOIC	DW	16	2000	346.0	346.0	33.0

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